

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Present Application:

Applicant : Tongbi Jiang Attorney Docket No. : 500180.03
Filed : Concurrently herewith Customer No. : 27,076
Title : METHOD OF PRESSURE CURING FOR REDUCING VOIDS IN A DIE
ATTACH BONDLINE AND APPLICATIONS THEREOF

Prior Application:

Examiner : Wai Sing Louie
Art Unit : 2814
Serial No. : 09/895,662

PRELIMINARY AMENDMENT

Mail Stop Box Patent Application
Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please amend the above-identified application as follows:

Amendments to the Title begin on page 2 of this paper.

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks begin on page 8 of this paper.